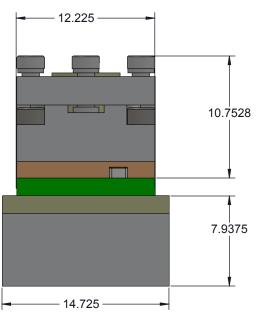
SM-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR TEST APPLICATIONS

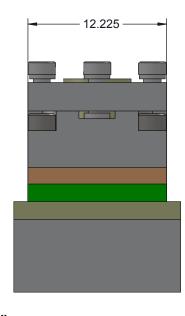
Features

- Wide temperature range (-55C to +150C).

- High current capability (up to 4A).
 Excellent signal integrity at high frequencies.
 Low and stable contact resistance for reliable production yield.
- Highly compliant to accommodate wide co-planarity variations.

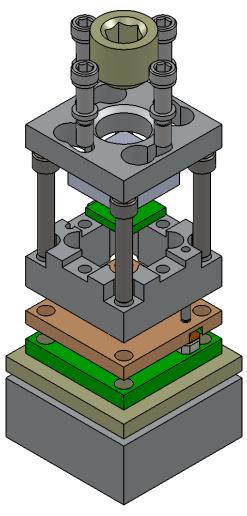
Top View





Side View

Front View



Description: SM-BGA81 9x9 0.5mm Pitch

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

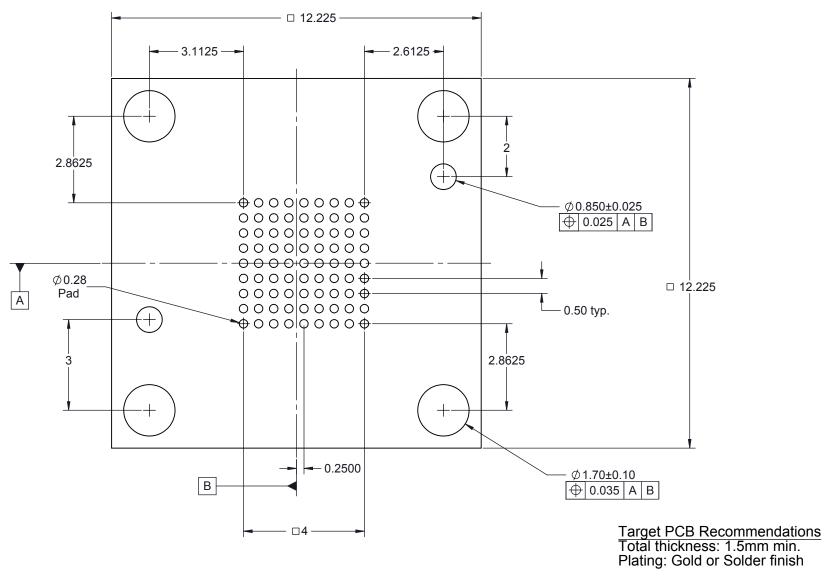
| SM-BGA-9020 Drawing | | |
|---------------------|-----------------------|--|
| | Ironwood Electronics, | |
| | Tele: (800) 404-020 | |

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodélectronics.com

Material: N/A Finish: N/A Weight: 8.63

| STATUS: Released | SHEET: 1 OF 4 REV. A | |
|--------------------|----------------------|--|
| DRAWN BY: B. Fedde | SCALE: 3:1 | |
| FILE: SM-BGA-9020 | DATE: 9/10/2012 | |

*Note: BGA pattern is not symmetrical with respect to the mounting holes.



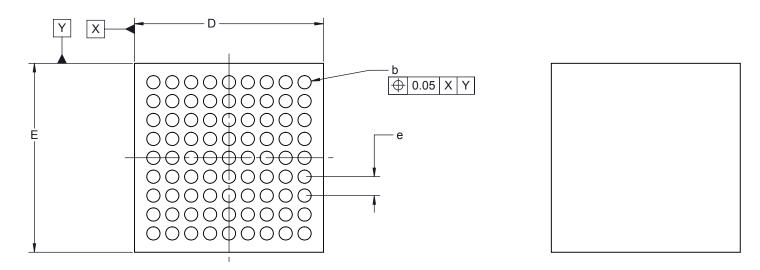
Description: Recommended PCB layout

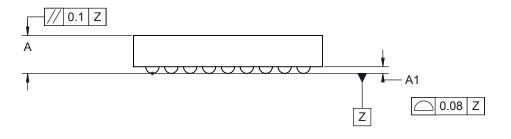
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9020 Drawing Material: N/A STATUS: Released SHEET: 2 OF 4 REV. A Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Tele: (800) 404-0204 Finish: N/A Weight: 8.63 DRAWN BY: B. Fedde SCALE: 8:1 FILE: SM-BGA-9020 DATE: 9/10/2012

IRONWOOD PACKAGE CODE: BGA81F1





| DIM | MIN | MAX |
|-----|------------|--|
| Α | | 1.0 |
| A1 | 0.15 | 0.25 |
| b | 0.25 | 0.35 |
| D | 5.0 BSC | |
| Е | 5.0 BSC | |
| е | 0.5 BSC | |
| | A A1 b D E | A 0.15 b 0.25 D 5.0 BSC E 5.0 BSC |

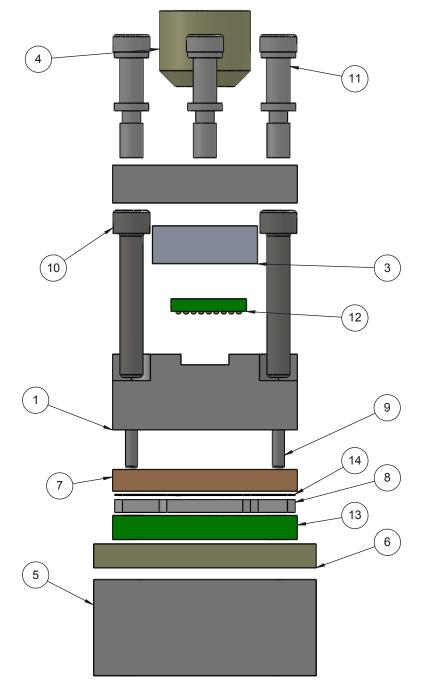
- 1. Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: BGA

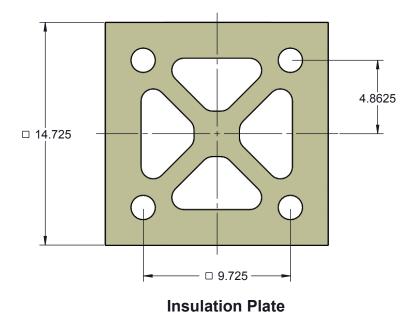
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

| SM-BGA-9020 Draw | ng Material: N/A | STATUS: Released | SHEET: 3 OF 4 REV. A |
|---|------------------|--------------------|----------------------|
| Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com | | DRAWN BY: B. Fedde | SCALE: 10:1 |
| | | FILE: SM-BGA-9020 | DATE: 9/10/2012 |



| ITEM NO. | DESCRIPTION | Material | Default/QTY. |
|-------------|---|-------------------------|--------------|
| 1 | Socket Base | 7075-T6 Aluminum Alloy | 1 |
| 2 | Socket Lid 7mm | 7075-T6 Aluminum Alloy | 1 |
| 3 | Compression Plate 7x7mm | 7075-T6 Aluminum Alloy | 1 |
| 4 | Compression Screw M6x1 | Stainless Steel (18-8) | 1 |
| 5 | Backing Plate | 7075-T6 Aluminum Alloy | 1 |
| 6 | Insulation Plate 7mm | FR4 Standard | 1 |
| 7 | 5mm SM IC Guide | Ultem 1000 | 1 |
| 8 | SM Interposer BGA 81 0.5mm | Silmat | 1 |
| 9 | Dowel Pin, 1/32" x 3/16", SS | Chrome Stainless Steel | 2 |
| 10 | #0-80 X .375 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE | Alloy Steel | 4 |
| 11 | #0-80 Shoulder Screw, 0.090" thread length | Stainless Steel (303) | 4 |
| 12 | Test Chip 9 x 9 0.5mm Pitch | FR4 Standard | 1 |
| 13 | Test PCB 5X5mm 9X9 0.5mm Pitch | FR4 High temp | 1 |
| 14 | Ball Guide, 9x9 BGA 0.5 pitch | Kapton Polyimide/Cirlex | 1 |



Description: Skt, Insulation Plate, Pin Det

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9020 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com

Material: N/A Finish: N/A Weight: 8.63

| STATUS: Released | SHEET: 4 OF 4 | REV. A |
|--------------------|-----------------|--------|
| DRAWN BY: B. Fedde | SCALE: 4:1 | |
| FILE: SM-BGA-9020 | DATE: 9/10/2012 | |